

MM74HC4020 • MM74HC4040

14-Stage Binary Counter • 12-Stage Binary Counter

General Description

The MM74HC4020, MM74HC4040, are high speed binary ripple carry counters. These counters are implemented utilizing advanced silicon-gate CMOS technology to achieve speed performance similar to LS-TTL logic while retaining the low power and high noise immunity of CMOS.

The MM74HC4020 is a 14 stage counter and the MM74HC4040 is a 12-stage counter. Both devices are incremented on the falling edge (negative transition) of the input clock, and all their outputs are reset to a low level by applying a logical high on their reset input.

These devices are pin equivalent to the CD4020 and CD4040 respectively. All inputs are protected from damage due to static discharge by protection diodes to V_{CC} and ground.

Features

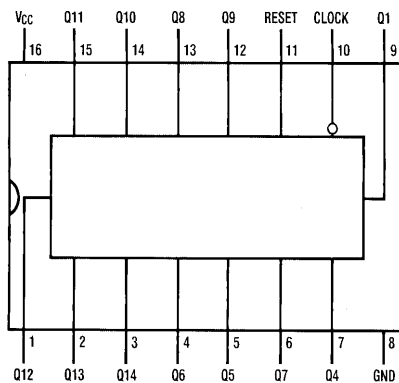
- Typical propagation delay: 16 ns
- Wide operating voltage range: 2–6V
- Low input current: 1 μ A maximum
- Low quiescent current: 80 μ A maximum (74HC Series)
- Output drive capability: 10 LS-TTL loads

Ordering Code:

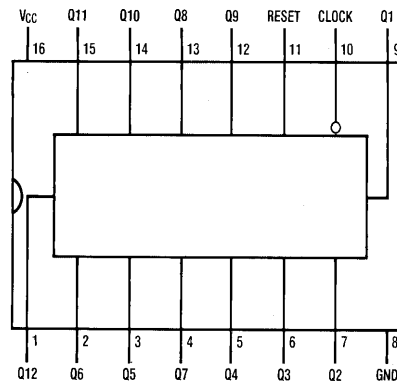
| Order Number | Package Number | Package Description |
|---------------|----------------|--|
| MM74HC4020M | M16A | 16-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow |
| MM74HC4020SJ | M16D | 16-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide |
| MM74HC4020N | N16E | 16-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide |
| MM74HC4040M | M16A | 16-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow |
| MM74HC4040SJ | M16D | 16-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide |
| MM74HC4040MTC | MTC16 | 16-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide |
| MM74HC4040N | N16E | 16-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide |

Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.

Connection Diagrams

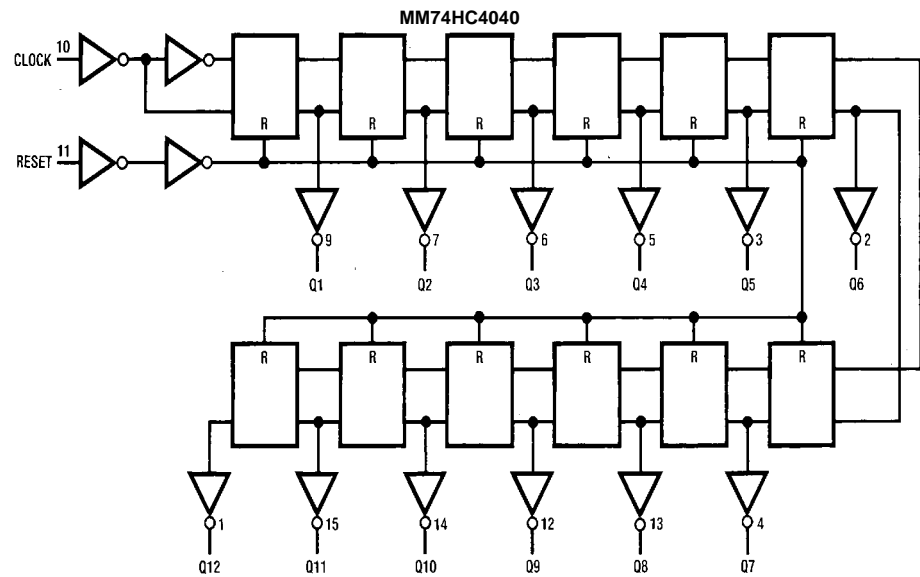
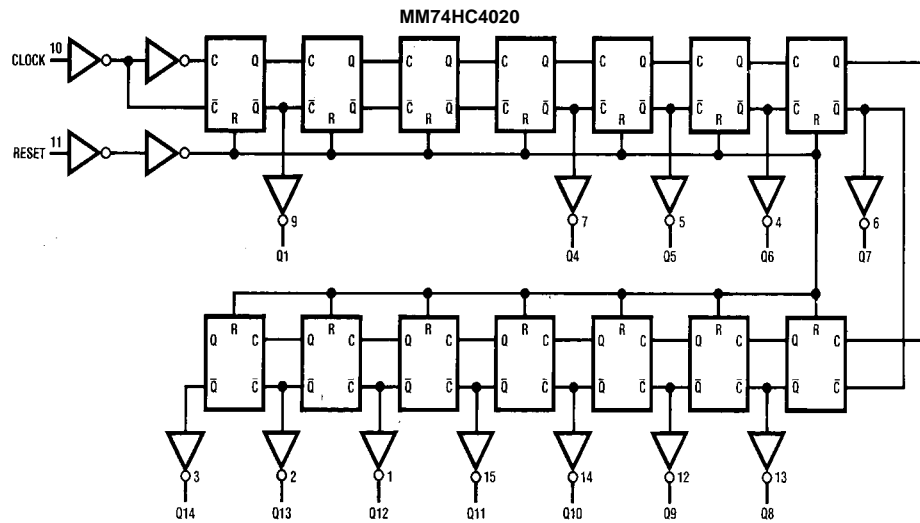


TOP VIEW
MM74HC4020



TOP VIEW
MM74HC4040

Logic Diagrams



Absolute Maximum Ratings(Note 1)

(Note 2)

| | |
|--|-------------------------|
| Supply Voltage (V_{CC}) | −0.5 to +7.0V |
| DC Input Voltage (V_{IN}) | −1.5 to $V_{CC} + 1.5V$ |
| DC Output Voltage (V_{OUT}) | −0.5 to $V_{CC} + 0.5V$ |
| Clamp Diode Current (I_{CD}) | ±20 mA |
| DC Output Current, per pin (I_{OUT}) | ±25 mA |
| DC V_{CC} or GND Current, per pin (I_{CC}) | ±50 mA |
| Storage Temperature Range (T_{STG}) | −65°C to +150°C |
| Power Dissipation (P_D) | |
| (Note 3) | 600 mW |
| S.O. Package only | 500 mW |
| Lead Temperature (T_L) | |
| (Soldering 10 seconds) | 260°C |

Recommended Operating Conditions

| | Min | Max | Units |
|---|-----|----------|-------|
| Supply Voltage (V_{CC}) | 2 | 6 | V |
| DC Input or Output Voltage (V_{IN} , V_{OUT}) | 0 | V_{CC} | V |
| Operating Temperature Range (T_A) | −40 | +85 | °C |
| Input Rise or Fall Times (t_r , t_f) $V_{CC} = 2.0V$ | | 1000 | ns |
| $V_{CC} = 4.5V$ | | 500 | ns |
| $V_{CC} = 6.0V$ | | 400 | ns |

Note 1: Maximum Ratings are those values beyond which damage to the device may occur.**Note 2:** Unless otherwise specified all voltages are referenced to ground.**Note 3:** Power Dissipation temperature derating — plastic "N" package: − 12 mW/°C from 65°C to 85°C.**DC Electrical Characteristics** (Note 4)

| Symbol | Parameter | Conditions | V _{CC} | T _A = 25°C | T _A = −40 to 85°C | T _A = −55 to 125°C | Units | |
|-----------------|-----------------------------------|--|-----------------|-----------------------|------------------------------|-------------------------------|-------|----|
| | | | | Typ | Guaranteed Limits | | | |
| V _{IH} | Minimum HIGH Level Input Voltage | | 2.0V | | 1.5 | 1.5 | 1.5 | V |
| | | | 4.5V | | 3.15 | 3.15 | 3.15 | V |
| | | | 6.0V | | 4.2 | 4.2 | 4.2 | V |
| V _{IL} | Maximum LOW Level Input Voltage | | 2.0V | | 0.5 | 0.5 | 0.5 | V |
| | | | 4.5V | | 1.35 | 1.35 | 1.35 | V |
| | | | 6.0V | | 1.8 | 1.8 | 1.8 | V |
| V _{OH} | Minimum HIGH Level Output Voltage | V _{IN} = V _{IH} or V _{IL} I _{OUT} ≤ 20 μA | 2.0V | 2.0 | 1.9 | 1.9 | 1.9 | V |
| | | | 4.5V | 4.5 | 4.4 | 4.4 | 4.4 | V |
| | | | 6.0V | 6.0 | 5.9 | 5.9 | 5.9 | V |
| | | V _{IN} = V _{IH} or V _{IL} I _{OUT} ≤ 4.0 mA I _{OUT} ≤ 5.2 mA | 4.5V | 4.2 | 3.98 | 3.84 | 3.7 | V |
| | | | 6.0V | 5.7 | 5.48 | 5.34 | 5.2 | V |
| | | | | | | | | |
| V _{OL} | Maximum LOW Level Output Voltage | V _{IN} = V _{IH} or V _{IL} I _{OUT} ≤ 20 μA | 2.0V | 0 | 0.1 | 0.1 | 0.1 | V |
| | | | 4.5V | 0 | 0.1 | 0.1 | 0.1 | V |
| | | | 6.0V | 0 | 0.1 | 0.1 | 0.1 | V |
| | | V _{IN} = V _{IH} or V _{IL} I _{OUT} ≤ 4.0 mA I _{OUT} ≤ 5.2 mA | 4.5V | 0.2 | .26 | 0.33 | 0.4 | V |
| | | | 6.0V | 0.2 | .26 | 0.33 | 0.4 | V |
| | | | | | | | | |
| I _{IN} | Maximum Input Current | V _{IN} = V _{CC} or GND | 6.0V | | ±0.1 | ±1.0 | ±1.0 | μA |
| I _{CC} | Maximum Quiescent Supply Current | V _{IN} = V _{CC} or GND I _{OUT} = 0 μA | 6.0V | | 8.0 | 80 | 160 | μA |

Note 4: For a power supply of 5V ±10% the worst case output voltages (V_{OH} , and V_{OL}) occur for HC at 4.5V. Thus the 4.5V values should be used when designing with this supply. Worst case V_{IH} and V_{IL} occur at $V_{CC} = 5.5V$ and 4.5V respectively. (The V_{IH} value at 5.5V is 3.85V.) The worst case leakage current (I_{IN} , I_{CC} , and I_{OZ}) occur for CMOS at the higher voltage and so the 6.0V values should be used.

AC Electrical Characteristics

$V_{CC} = 5V$, $T_A = 25^\circ C$, $C_L = 15\text{ pF}$, $t_r = t_f = 6\text{ ns}$

| Symbol | Parameter | Conditions | Typ | Guaranteed Limit | Units |
|-----------------------|--|------------|-----|------------------|-------|
| f_{MAX} | Maximum Operating Frequency | | 50 | 30 | MHz |
| t_{PHL} , t_{PLH} | Maximum Propagation Delay Clock to Q | (Note 5) | 17 | 35 | ns |
| t_{PHL} | Maximum Propagation Delay Reset to any Q | | 16 | 40 | ns |
| t_{REM} | Minimum Reset Removal Time | | 10 | 20 | ns |
| t_W | Minimum Pulse Width | | 10 | 16 | ns |

Note 5: Typical Propagation delay time to any output can be calculated using: $t_p = 17 + 12(N-1)\text{ ns}$; where N is the number of the output, Q_W , at $V_{CC} = 5V$.

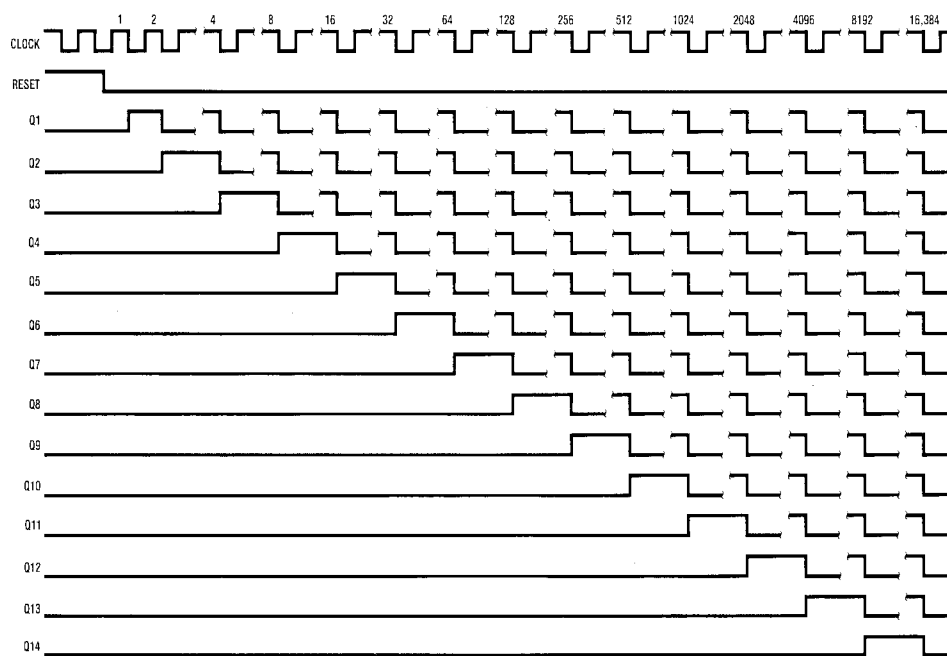
AC Electrical Characteristics

$V_{CC} = 2.0V$ to $6.0V$, $C_L = 50\text{ pF}$, $t_r = t_f = 6\text{ ns}$ (unless otherwise specified)

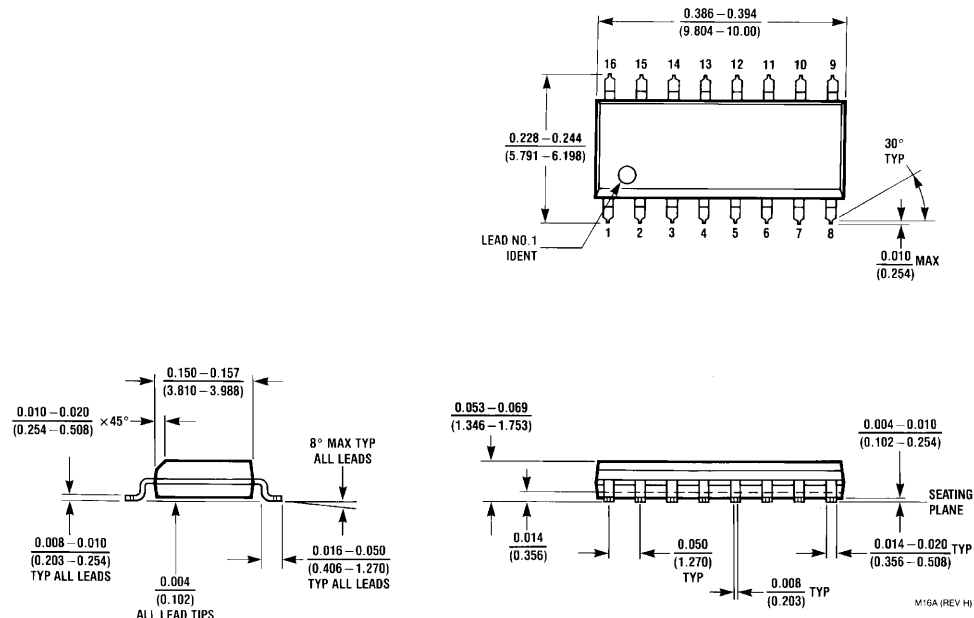
| Symbol | Parameter | Conditions | V _{CC} | T _A = 25°C | | T _A = −40 to 85°C | T _A = −55 to 125°C | Units |
|-------------------------------------|--|---------------|-----------------|-----------------------|-------------------|------------------------------|-------------------------------|-------|
| | | | | Typ | Guaranteed Limits | | | |
| t _{MAX} | Maximum Operating Frequency | | 2.0V | 10 | 6 | 5 | 4 | MHz |
| | | | 4.5V | 40 | 30 | 24 | 20 | MHz |
| | | | 6.0V | 50 | 35 | 28 | 24 | MHz |
| t _{PHL} , t _{PLH} | Maximum Propagation Delay Clock to Q ₁ | | 2.0V | 80 | 210 | 265 | 313 | ns |
| | | | 4.5V | 21 | 42 | 53 | 63 | ns |
| | | | 6.0V | 18 | 36 | 45 | 53 | ns |
| T _{PHL} , t _{PLH} | Maximum Propagation Delay Between Stages from Q _n to Q _{n+1} | | 2.0V | 80 | 125 | 156 | 188 | ns |
| | | | 4.5V | 18 | 25 | 31 | 38 | ns |
| | | | 6.0V | 15 | 21 | 26 | 31 | ns |
| t _{PHL} | Maximum Propagation Delay Reset to any Q (4020 and 4040) | | 2.0V | 72 | 240 | 302 | 358 | ns |
| | | | 4.5V | 24 | 48 | 60 | 72 | ns |
| | | | 6.0V | 20 | 41 | 51 | 61 | ns |
| t _{REM} | Minimum Reset Removal Time | | 2.0V | | 100 | 126 | 149 | ns |
| | | | 4.5V | | 20 | 25 | 50 | ns |
| | | | 6.0V | | 16 | 21 | 25 | ns |
| t _W | Minimum Pulse Width | | 2.0V | | 90 | 100 | 120 | ns |
| | | | 4.5V | | 16 | 20 | 24 | ns |
| | | | 6.0V | | 14 | 18 | 20 | ns |
| t _{TLH} , t _{THL} | Maximum Output Rise and Fall Time | | 2.0V | 30 | 75 | 95 | 110 | ns |
| | | | 4.5V | 10 | 15 | 19 | 22 | ns |
| | | | 6.0V | 9 | 13 | 16 | 19 | ns |
| t _r , t _f | Maximum Input Rise and Fall Time | | | | 1000 | 1000 | 1000 | ns |
| | | | | | 500 | 500 | 500 | ns |
| | | | | | 400 | 400 | 400 | ns |
| C _{PD} | Power Dissipation Capacitance (Note 6) | (per package) | | 55 | | | | pF |
| C _{IN} | Maximum Input Capacitance | | | 5 | 10 | 10 | 10 | pF |

Note 6: C_{PD} determines the no load dynamic power consumption, $P_D = C_{PD} V_{CC}^2 f + I_{CC} V_{CC}$, and the no load dynamic current consumption, $I_S = C_{PD} V_{CC} f + I_{CC}$.

Timing Diagram

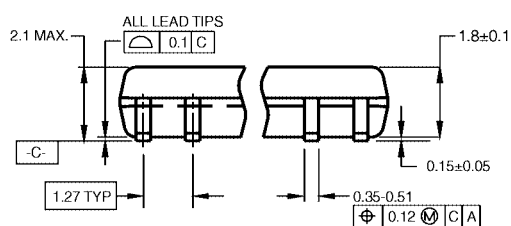
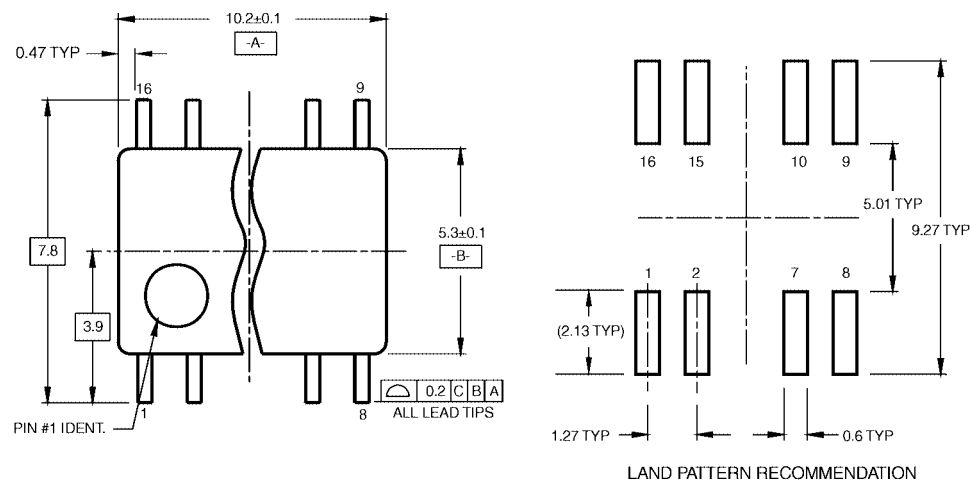


Physical Dimensions inches (millimeters) unless otherwise noted



16-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow
Package Number M16A

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)

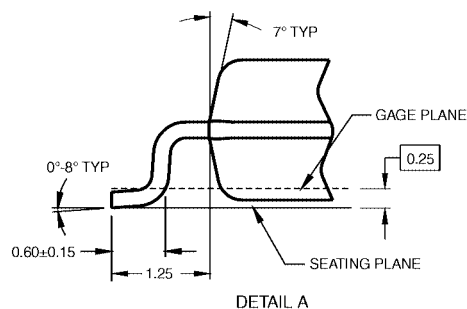


DIMENSIONS ARE IN MILLIMETERS

NOTES:

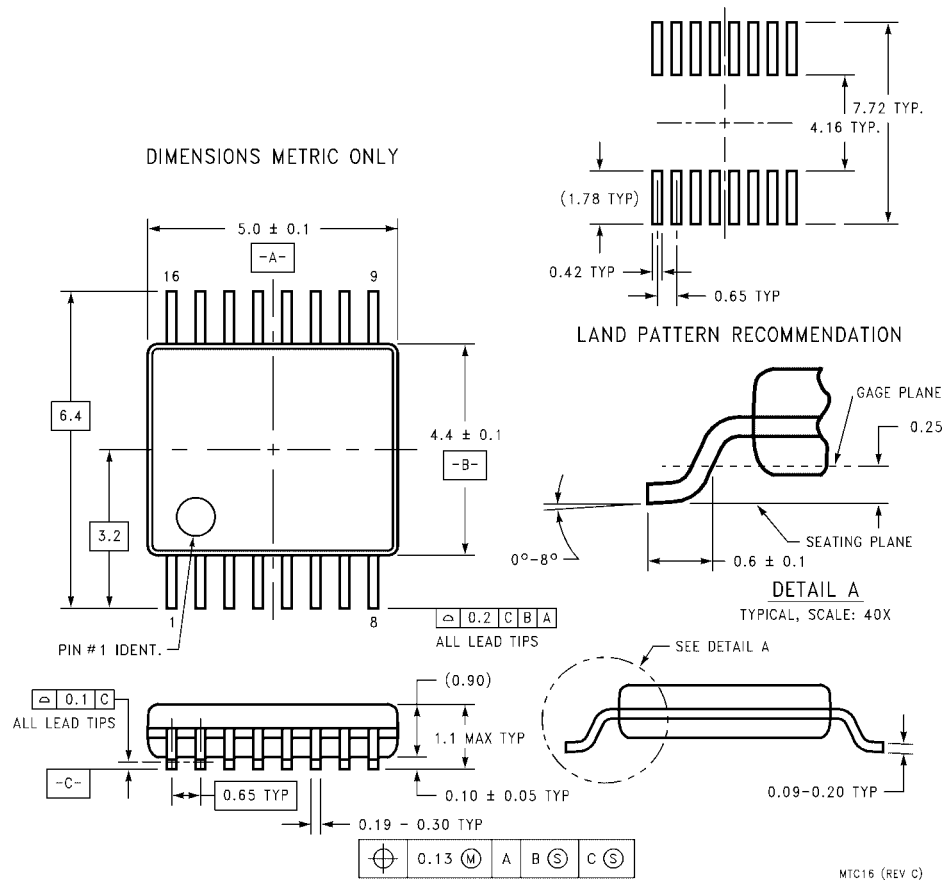
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- DIMENSIONS ARE IN MILLIMETERS.
- DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.

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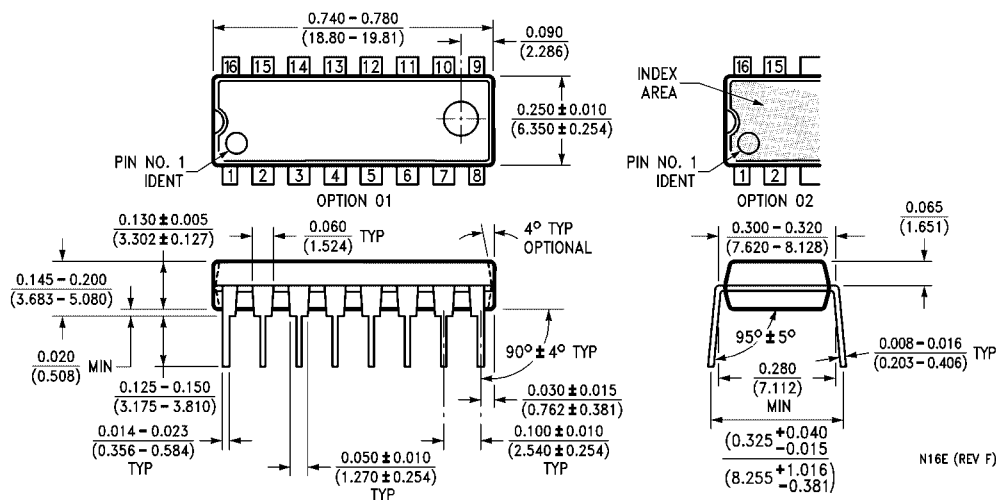


16-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
Package Number M16D

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



**16-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide
Package Number MTC16**

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)

**16-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide
Package Number N16E**

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